MURD320

SWITCHMODE Power Rectifier

DPAK Surface Mount Package

These state-of-the-art devices are designed for use in switching power supplies, inverters and as free wheeling diodes.

Features

- Ultrafast 35 Nanosecond Recovery Time
- Low Forward Voltage Drop
- Low Leakage
- Pb-Free Package is Available

Mechanical Characteristics

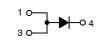
- Case: Epoxy, Molded
- Weight: 0.4 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Available in 16 mm Tape and Reel, 2500 Units Per Reel, by Adding a "T4" Suffix to the Part Number



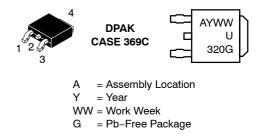
ON Semiconductor®

http://onsemi.com

ULTRAFAST RECTIFIER 3.0 AMPERES, 200 VOLTS







MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	200	V
Average Rectified Forward Current (Rated V _R , T _C = 158°C)	I _{F(AV)}	3.0	A
Peak Repetitive Forward Current (Rated V _R , Square Wave, 20 kHz, T _C = 158°C)	I _{FRM}	6.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, 60 Hz)	I _{FSM}	75	A
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-65 to +175	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

ORDERING INFORMATION

Device	Package	Shipping [†]
MURD320T4	DPAK	2500/Tape & Reel
MURD320T4G	DPAK (Pb-Free)	2500/Tape & Reel

+ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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THERMAL CHARACTERISTICS

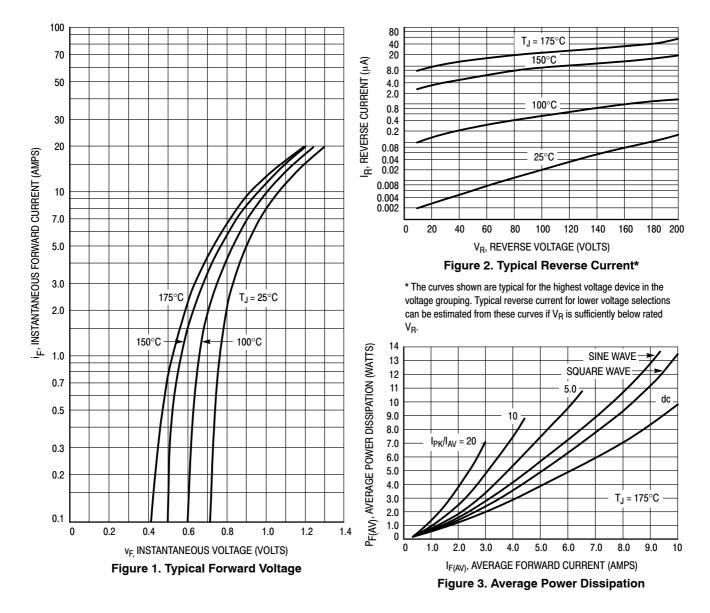
Rating	Symbol	Value	Unit
Thermal Resistance – Junction-to-Case	$R_{\theta JC}$	6	°C/W
Thermal Resistance – Junction-to-Ambient (Note 1)	$R_{\theta JA}$	80	°C/W

ELECTRICAL CHARACTERISTICS

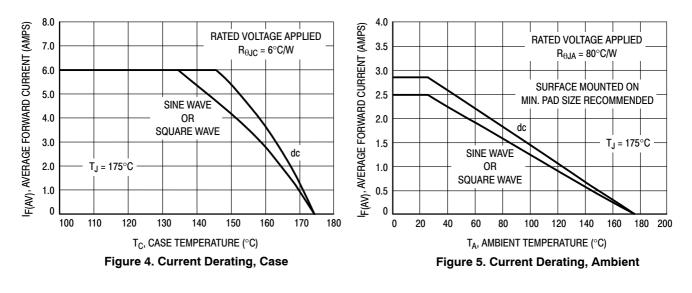
Maximum Instantaneous Forward Voltage Drop (Note 2) ($i_F = 3 \text{ Amps}, T_J = 25^{\circ}\text{C}$) ($i_F = 3 \text{ Amps}, T_J = 125^{\circ}\text{C}$)	VF	0.95 0.75	Volts
Maximum Instantaneous Reverse Current (Note 2) $(T_J = 25^{\circ}C, Rated dc Voltage)$ $(T_J = 125^{\circ}C, Rated dc Voltage)$	İR	5 500	μΑ
	t _{rr}	35 25	ns

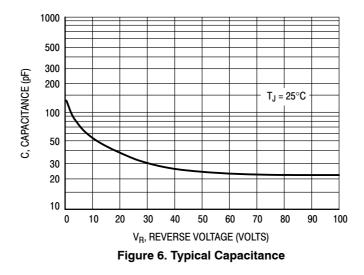
1. Rating applies when surface mounted on the minimum pad sizes recommended.

2. Pulse Test: Pulse Width = 300 $\mu s,$ Duty Cycle \leq 2.0%.



MURD320



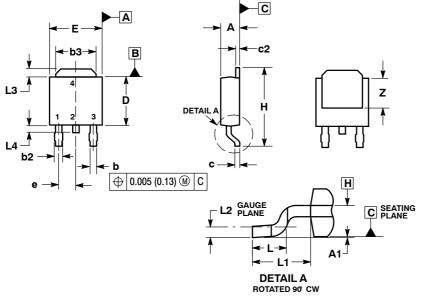


MURD320

PACKAGE DIMENSIONS

DPAK (SINGLE GAUGE)

CASE 369C-01 ISSUE D

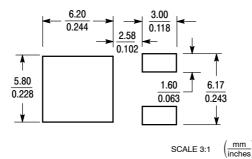


NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: INCHES.
 THERMAL PAD CONTOUR OPTIONAL WITHIN DI-
- THERMAL PAD CONTOUR OPTIONAL WITHIN DI-MENSIONS b3, L3 and Z.
 DIMENSIONS D AND E DO NOT INCLUDE MOLD
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE
- NOT EXCEED 0.006 INCHES PER SIDE. 5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- 6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.030	0.045	0.76	1.14
b3	0.180	0.215	4.57	5.46
С	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
е	0.090 BSC		2.29 BSC	
н	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.108 REF		2.74 REF	
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4		0.040		1.01
Z	0.155		3.93	

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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